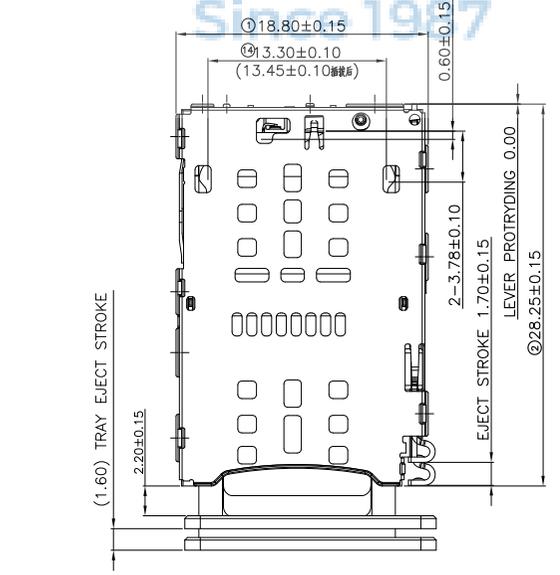
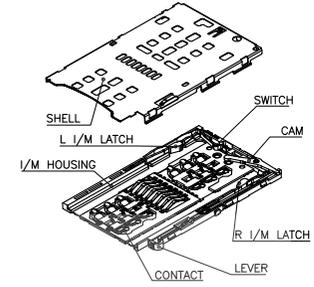
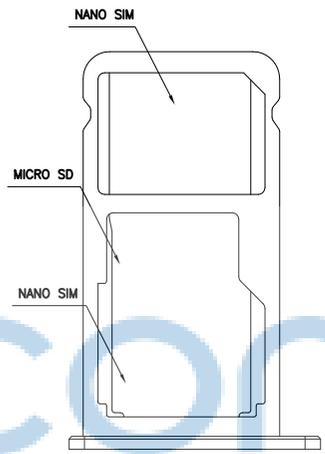
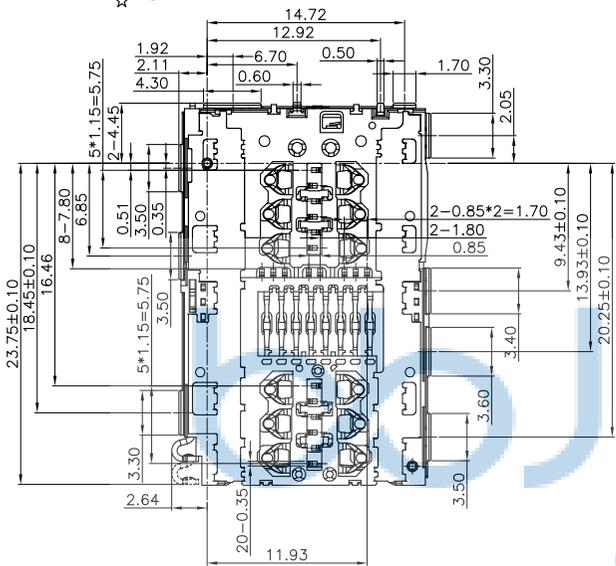
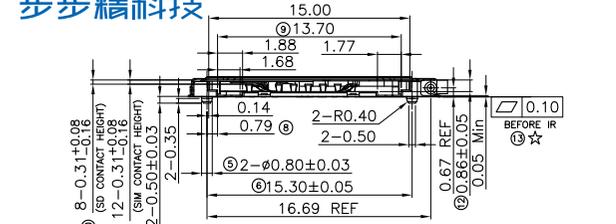


REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF

- NOTES:
- FINISH
 - CONTACT-CONTACT AREA: GOLD FLASH; SW AREA: GOLD FLASH; GOLD PLATING ON SOLDER AREA, GOLD FLASH.
 - SHELL: SOLDER AREA: GOLD FLASH.
 - ELECTRICAL REQUIREMENTS:
 - CURRENT RATING: 0.3A PER PIN.
 - CURRENT VOLTAGE: 50V MAX.
 - CONTACT RESISTANCE: 60 mOhm MAX. AFTER TEST:100 mOhm MAX SWITCH RESISTANCE : 100 mOhm MAX. AFTER TEST:150 mOhm MAX
 - INSULATION RESISTANCE: 1000 MOhm MIN.200 VDC FOR 1 MINUTE.
 - WITHSTANDING STRENGTH: 500V AC FOR 1 MINUTE.
 - MECHANICAL REQUIREMENTS:
 - TRAY MATING FORCE: 2~10N ; TRAY UNMATING FORCE: 6~10N OPERATING FORCE: 4~15N . THE RESORPTION DISTANCE OF THE TRAY : 0.4mm MIN
 - DURABILITY: 3,000 CYCLES MIN.
 - ENVIRONMENT REQUIREMENTS:
 - OPERATING TEMP.: -30°C TO +85°C
 - STORAGE TEMPERATURE: -40°C TO +85°C
 - THE DIMENSION ⊕ SHOULD BE CHECKED BY QC, AND MARKED ☆ SHOULD CHECK THE CPK DATA.



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ITEM	PART NAME	Q'TY	MATERIAL	FINISH
8	Switch	1	Copper alloy	Plating Ni 30~200u' over all SWITCH AREA: Au 15u" min. SOLDER AREA: Au 3u" min.
7	L I/M Latch	1	SUS301+Nylon	NO PLATING, Black Plastic
6	R I/M Latch	1	SUS301+Nylon	NO PLATING, Black Plastic
5	CAM	1	SUS304	NO PLATING
4	LEVER	1	SUS301	NO PLATING
3	SHELL	1	SUS301	Plating Ni 10~50u' over all SOLDER AREA: Au 3u" min.
2	I/M HOUSING	1	LCP	BLACK COLOR, UL94 V-0
1	CONTACT	1	Copper alloy	Plating Ni 30~200u' over all CONTACT AREA: Au 15u" min. SWITCH AREA: Au 5u" min. SOLDER AREA: Au 3u" min.

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PDWG.NO: 0302-1

APPD. JM_Zheng

CHKD. LYX

DR. SGF

深圳市步步精科技有限公司

NAME: 卡座 1.35H 双NANO+T 三选二 SIM LCP黑胶 接触区镀金G-F

PJ. NO.: 142-201-080001-V8G

SIZE: A4 DRW NO.:

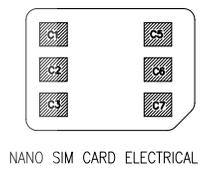
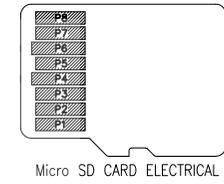
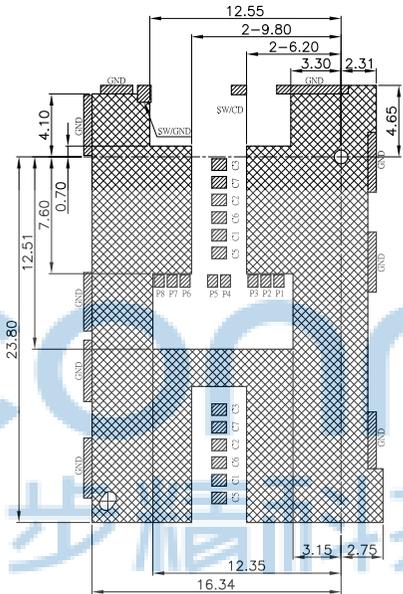
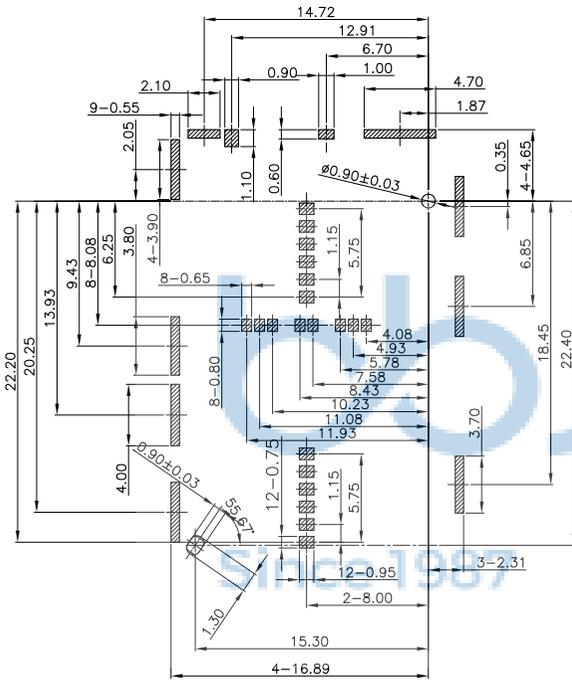
FINISH: SEE NOTES MAT'L.: SEE NOTES

SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/3

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF

CONNECTOR PIN ASSIGNMENT:

ITEM	FUNCTION
Micro SD CARD	
P1	DAT2 OF MSD
P2	CD/DAT3 OF MSD
P3	CMD OF MSD
P4	VDD OF MSD
P5	CLK OF MSD
P6	VSS OF MSD
P7	DAT0 OF MSD
P8	DAT1 OF MSD
SW	TRAY DETECTION SW
S	SHELL GND
NANO SIM CARD	
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	DATA OF SIM



CARD PIN ASSIGNMENT:

ITEM	FUNCTION
Micro SD CARD	
P1	DAT2 OF MSD
P2	CD/DAT3 OF MSD
P3	CMD OF MSD
P4	VDD OF MSD
P5	CLK OF MSD
P6	VSS OF MSD
P7	DAT0 OF MSD
P8	DAT1 OF MSD
NANO SIM CARD	
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	DATA OF SIM



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NAME: 卡座 1.35H 双NANO+T 三选二 SIM LCP黑胶 接触区镀金G-F

PJ. NO.: 142-201-080001-V8G

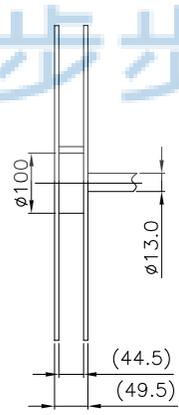
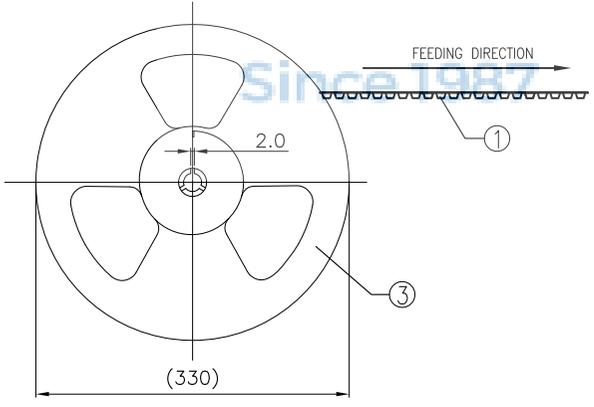
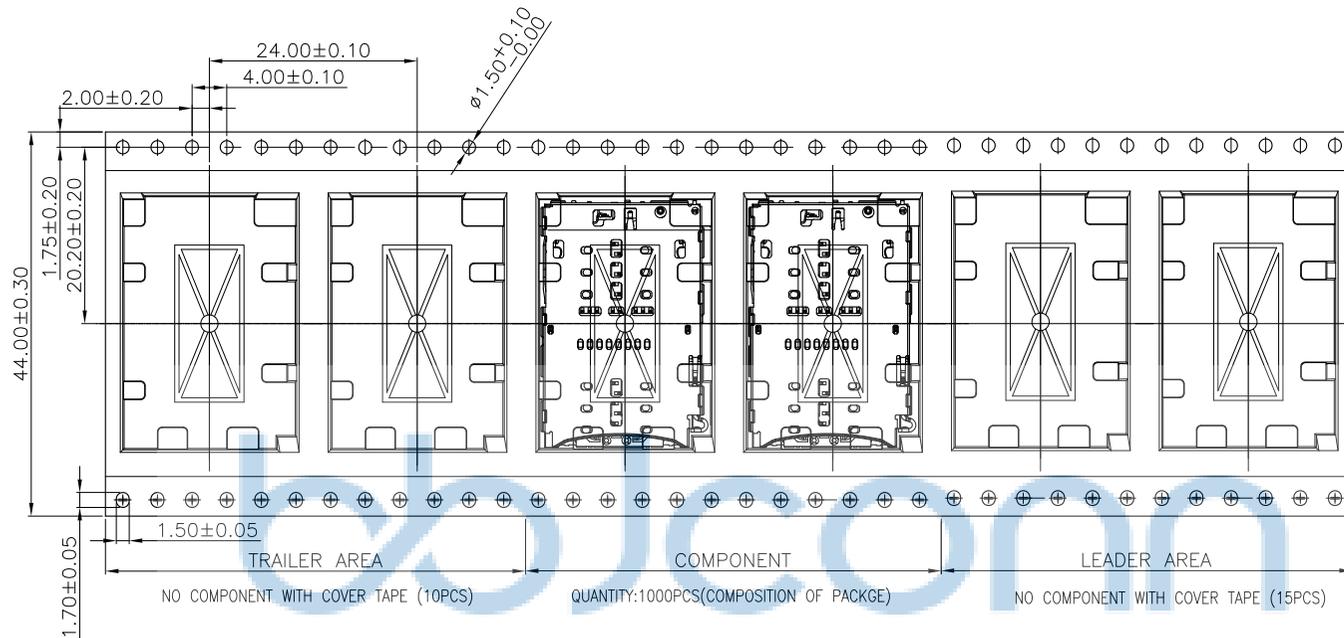
SIZE: A4 | DRW NO.:

FINISH: SEE NOTES | MAT'L.: SEE NOTES

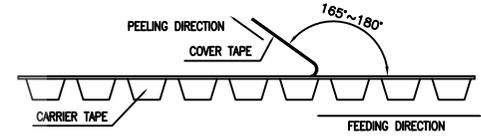
SCALE: N/A | REV.: A0 | UNIT: mm | PAGE: 2/3

深圳市步步精科技有限公司

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF



- NOTES:
- 1, POCKET HOLE PITCH CLUMATIVE TOLERANCE $\pm 0.40\text{mm}$
 - 2, COVER TAPE PEELING STRENGTH : 30~100gf AT 300mm/MIN



- 3, Packaging capacity:
1000pcs/REEL; 6REEL/CARTON ; TOTAL: 6000PCS/CARTON
- 4, Packaging Use Attention:
NOT TWISTED OVER 90° WITHIN 1000mm.



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APPD.	JM_Zheng	PJ. NO.: 142-201-080001-V8G		SIZE: A4 DRW NO.:	
CHKD.	LYX	FINISH: SEE NOTES		MAT'L.: SEE NOTES	
PDWG.NO:	0302-1	DR.	SGF	SCALE: N/A	REV.: A0 UNIT: mm PAGE: 3/3